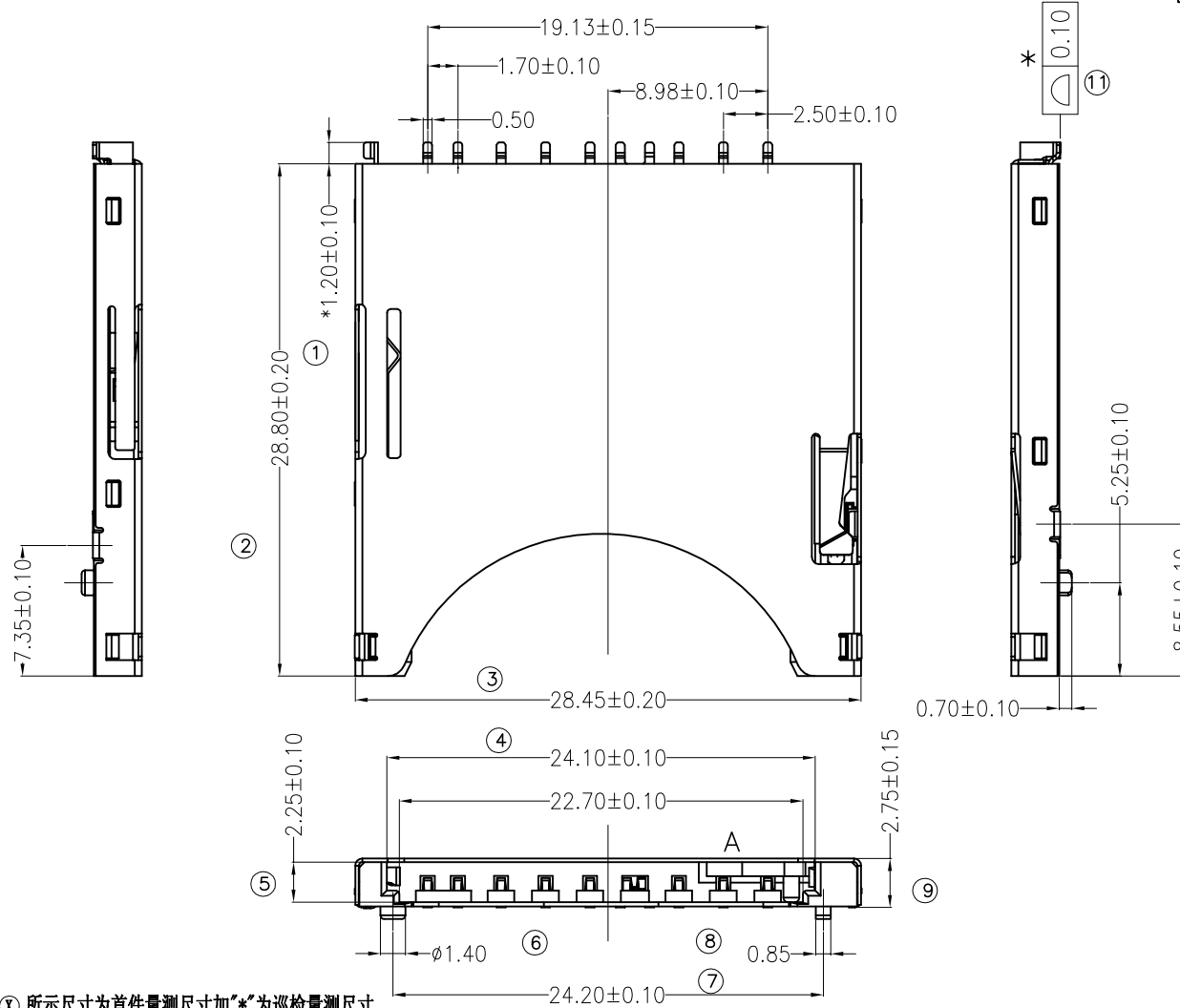


* 所有原料材质, 生产制程, 电镀必须符合ROHS要求



备注:加 ⑩ 所示尺寸为首件量测尺寸加"*"为巡检量测尺寸

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic,
UL 94V-0.

Contact: Copper Alloy

PLATING:

Contact: Plated 50u" Ni Overall

Plated Au Selective Contact Area

Plated 100u" Sn Over Ni On Solder Area

Shell: Plated 50u" Ni Overall

Plated 1u" Au Over Ni On Solder Area

Electrical:

Current Rating :0.5mA AC/DC max.

Voltage Rating :125V AC/DC

Ambient Temperature Range :-20°C~+60°C

Storage Temperature Range :-40°C~+70°C

Ambient Humidity Range :95% R.H. Max.

Contact Resistance:100mΩ max.

Insulation Resistance:1000MΩ min./500VDC

Mating Cycles:10,000 Insertions

Usable Memory Card:

SD&MMC Card

Pin No.	SD	MMC
P1	MMC-DAT SD-DAT3	1P
P2	MMC-CMD SD-CMD	2P
P3	MMC-VSS1 SD-VSS1	3P
P4	MMC-VDD SD-VDD	4P
P5	MMC-CLK SD-CLK	5P
P6	MMC-VSS2 SD-VSS2	6P
P7	MMC-DAT SD-DAT0	7P
P8	SD-DAT1	8P
P9	SD-DAT2	9P

CIRCUIT:



GROUND
WITHOUT CARD

GROUND
SD CARD INSERTED
WRITE PROTECT:LOCK

GROUND
1.SD CARD INSERTED
WRITE PROTECT:UNLOCK
2.OTHER CARD INSERTED



东莞市汉博电子科技有限公司
Dongguan Hanbo Electronic Technology Co., Ltd

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.25
X.XX: ±	0.10
X.XXX: ±	0.05
ANGULAR: ±	1°

PRODUCT NAME :
SD push-push

PRODUCT NO. :
SD-111

DRAWING NO. :
NT-001

DRAWING:
COCO

CHECK:
JANY

APPROVED:
JEFF

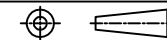
SCALE:
1:1

DATE:
2008/12/10

DATE:
2008/12/10

DATE:
2008/12/10

REV.:
A



DWG ID:
P D

PAGE:
1 of 3

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				